# Low Power Programmable Oscillator



### **Features**

- Any frequency between 1 MHz and 110 MHz accurate to 6 decimal places
- Operating temperature from -40°C to 85°C. Refer to SiT8918 and SiT8920 for high temperature options
- Excellent total frequency stability as low as ±20 PPM
- Low power consumption of 3.6 mA typical
- Programmable drive strength for improved jitter, system EMI reduction, or driving large capacitive loads
- LVCMOS/HCMOS compatible output
- Industry-standard packages: 2.0 x 1.6, 2.5 x 2.0, 3.2 x 2.5, 5.0 x 3.2, 7.0 x 5.0 mm x mm
- Instant samples with Time Machine II and field programmable oscillators
- Pb-free, RoHS and REACH compliant

### **Applications**

- Ideal for DSC, DVC, DVR, IP CAM, Tablets, e-Books, SSD, GPON, EPON, etc
- Ideal for high-speed serial protocols such as: USB, SATA, SAS, Firewire, 100M / 1G / 10G Ethernet, etc.







### Electrical Characteristics[1]

Parameter and Conditions	Symbol	Min.	Тур.	Max.	Unit	Condition
			Fi	requency R	ange	
Output Frequency Range	f	1	-	110	MHz	
			Frequen	cy Stability	and Aging	
Frequency Stability	F_stab	-20	-	+20	PPM	Inclusive of Initial tolerance at 25°C, 1st year aging at 25°C, and
		-25	-	+25	PPM	variations over operating temperature, rated power supply voltage and load (15 pF ± 10%).
		-50	-	+50	PPM	10.00g0 0.00 (10 pt = 10.74)
			Operatir	ng Tempera		
Operating Temperature Range	T_use	-20	-	+70	°C	Extended Commercial
		-40	-	+85	°C	Industrial
			upply Voltag			
Supply Voltage	Vdd	1.62	1.8	1.98	V	Contact SiTime for 1.5V support
		2.25	2.5	2.75	V	
		2.52	2.8	3.08	V	
		2.7	3.0	3.3	V	
		2.97	3.3	3.63	V	
		2.25	-	3.63	V	
Current Consumption	ldd	_	3.8	4.5	mA	No load condition, f = 20 MHz, Vdd = 2.8V, 3.0V, 3.3V, 2.25V to 3.63V
		_	3.6	4.2	mA	No load condition, f = 20 MHz, Vdd = 2.5V
		_	3.4	3.9	mA	No load condition, f = 20 MHz, Vdd = 1.8V
OE Disable Current	I_OD	_	-	4	mA	Vdd = 2.5V to 3.3V, OE = GND, output is Weakly Pulled Down
		_	-	3.8	mA	Vdd = 1.8V, OE = GND, output is Weakly Pulled Down
Standby Current	I_std	_	2.6	4.3	μΑ	$\overline{ST}$ = GND, Vdd = 2.8V to 3.3V, Output is Weakly Pulled Down
		_	1.4	2.5	μΑ	ST = GND, Vdd = 2.5V, Output is Weakly Pulled Down
		_	0.6	1.3	μΑ	ST = GND, Vdd = 1.8V, Output is Weakly Pulled Down
			LVCMOS	Output Cha		·
Duty Cycle	DC	45	-	55	%	All Vdds
Rise/Fall Time	Tr, Tf	_	1	2	ns	Vdd = 2.5V, 2.8V, 3.0V or 3.3V, 20% - 80%
		_	1.3	2.5	ns	Vdd =1.8V, 20% - 80%
		-	-	2	ns	Vdd = 2.25V - 3.63V, 20% - 80%
Output High Voltage	VOH	90%	_	_	Vdd	IOH = -4 mA (Vdd = 3.0V or 3.3V) IOH = -3 mA (Vdd = 2.8V and Vdd = 2.5V)
						IOH = -2 mA (Vdd = 1.8V)
Output Low Voltage	VOL	-	_	10%	Vdd	IOL = 4 mA (Vdd = 3.0V or 3.3V) IOL = 3 mA (Vdd = 2.8V and Vdd = 2.5V) IOL = 2 mA (Vdd = 1.8V)
			Inn	ut Characte	ristics	10L - 2 Hirt (vad - 1.0v)
Input High Voltage	VIH	70%		_	Vdd	Pin 1, OE or ST
Input Low Voltage	VIII	-	_	30%	Vdd	Pin 1, OE or ST
Input Pull-up Impedence	Z_in	_	87	100	kΩ	Pin 1, OE logic high or logic low, or ST logic high
mpact an-up impedence	"'	2	-	-	MΩ	Pin 1, ST logic low
Note:	1	_	<u> </u>			in i, or logic low

1. All electrical specifications in the above table are specified with 15 pF output load at default drive strength and for all Vdd(s) unless otherwise stated.

SiTime Corporation 990 Almanor Avenue Sunnyvale, CA 94085 (408) 328-4400 www.sitime.com

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# Low Power Programmable Oscillator



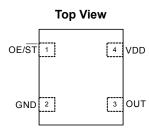
# Electrical Characteristics<sup>[1]</sup> (continued)

Parameter and Conditions	Symbol	Min.	Тур.	Max.	Unit	Condition			
Startup and Resume Timing									
Startup Time T_start - 5 ms Measured from the time Vdd reaches its rated minimum value									
Enable/Disable Time	T_oe	_	_	130	ns	f = 110 MHz. For other frequencies, T_oe = 100 ns + 3 * cycles			
Resume Time	T_resume	_	_	5	ms	Measured from the time ST pin crosses 50% threshold			
				Jitter					
RMS Period Jitter	T_jitt	_	1.76	3	ps	f = 75 MHz, Vdd = 2.5V, 2.8V, 3.0V or 3.3V			
		_	1.78	3	ps	f = 75 MHz, Vdd = 1.8V			
RMS Phase Jitter (random)	T_phj	_	0.5	0.9	ps	f = 75 MHz, Integration bandwidth = 900 kHz to 7.5 MHz			
		-	1.3	2	ps	f = 75 MHz, Integration bandwidth = 12 kHz to 20 MHz			

### Note:

### **Pin Description**

Pin	Symbol		Functionality
	Output Enab		H or Open <sup>[2]</sup> : specified frequency output L: output is high impedance. Only output driver is disabled.
1	1 OE/ ST Standby	Standby	H or Open <sup>[2]</sup> : specified frequency output L: output is low (weak pull down). Device goes to sleep mode. Supply current reduces to I_std.
2	GND	Power	Electrical ground <sup>[3]</sup>
3	OUT	Output	Oscillator output
4	VDD	Power	Power supply voltage <sup>[3]</sup>



#### Notes:

- 2. A pull-up resistor of <10 k $\Omega$  between OE/ $\overline{\text{ST}}$  pin and Vdd is recommended in high noise environment. 3. A capacitor value of 0.1  $\mu\text{F}$  between Vdd and GND is recommended.

### **Absolute Maximum**

Attempted operation outside the absolute maximum ratings of the part may cause permanent damage to the part. Actual performance of the IC is only guaranteed within the operational specifications, not at absolute maximum ratings.

Parameter	Min.	Max.	Unit
Storage Temperature	-65	150	°C
VDD	-0.5	4	V
Electrostatic Discharge	-	2000	V
Soldering Temperature (follow standard Pb free soldering guidelines)	-	260	°C
Junction Temperature	-	150	°C

### **Thermal Consideration**

Package	θJA, 4 Layer Board (°C/W)	θJA, 2 Layer Board (°C/W)	θJC, Bottom (°C/W)
7050	191	263	30
5032	97	199	24
3225	109	212	27
2520	117	222	26
2016	124	227	26

### **Environmental Compliance**

Parameter	Condition/Test Method
Mechanical Shock	MIL-STD-883F, Method 2002
Mechanical Vibration	MIL-STD-883F, Method 2007
Temperature Cycle	JESD22, Method A104
Solderability	MIL-STD-883F, Method 2003
Moisture Sensitivity Level	MSL1 @ 260°C

<sup>1.</sup> All electrical specifications in the above table are specified with 15 pF output load and for all Vdd(s) unless otherwise stated.



# Test Circuit and Waveform<sup>[4]</sup>

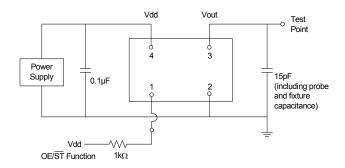


Figure 1. Test Circuit

### Note:

4. Duty Cycle is computed as Duty Cycle = TH/Period.

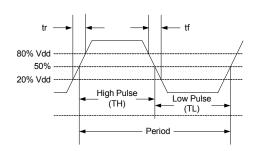


Figure 2. Waveform

# **Timing Diagrams**

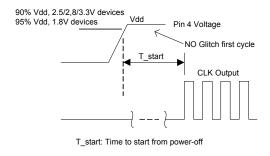
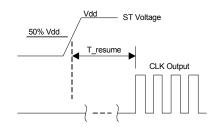
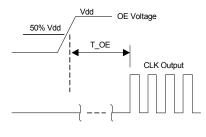


Figure 3. Startup Timing (OE/ST Mode)



T\_resume: Time to resume from ST

Figure 4. Standby Resume Timing (ST Mode Only)



T\_OE: Time to re-enable the clock output

OE Voltage

| 50% Vdd |
| T\_OE |
| T\_OE

T\_OE: Time to put the output drive in High Z mode

Figure 5. OE Enable Timing (OE Mode Only)

Note:

5. SiT8008 supports no runt pulses and no glitches during startup or resume.

Figure 6. OE Disable Timing (OE Mode Only)



### **Performance Plots**

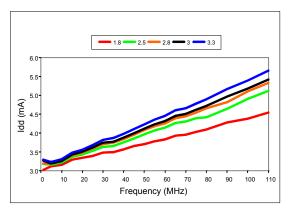


Figure 7. Idd vs Frequency

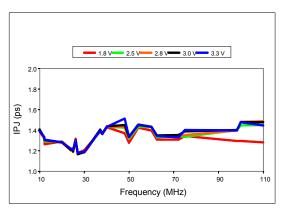


Figure 9. RMS Phase Jitter vs Frequency (12 kHz to 20 MHz Integration Bandwidth)

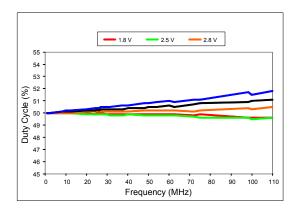


Figure 11. Duty Cycle vs Frequency

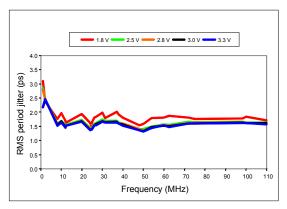


Figure 8. RMS Period Jitter vs Frequency

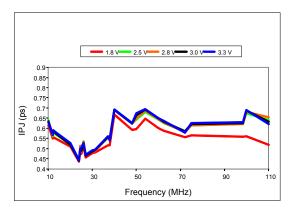


Figure 10. RMS Phase Jitter vs Frequency (900 kHz to 20 MHz Integration Bandwidth)

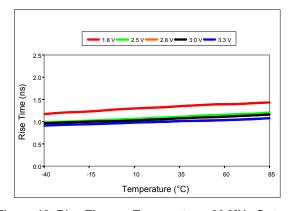


Figure 12. Rise Time vs Temperature, 20 MHz Output

### Note:

6. All plots are measured with 15 pF load at room temperature, unless otherwise stated.

### **Low Power Programmable Oscillator**



### **Programmable Drive Strength**

The SiT8008 includes a programmable drive strength feature to provide a simple, flexible tool to optimize the clock rise/fall time for specific applications. Benefits from the programmable drive strength feature are:

- Improves system radiated electromagnetic interference (EMI) by slowing down the clock rise/fall time
- Improves the downstream clock receiver's (RX) jitter by decreasing (speeding up) the clock rise/fall time.
- Ability to drive large capacitive loads while maintaining full swing with sharp edge rates.

For more detailed information about rise/fall time control and drive strength selection, see the SiTime Applications Note section; http://www.sitime.com/support/application-notes.

### **EMI Reduction by Slowing Rise/Fall Time**

Figure 13 shows the harmonic power reduction as the rise/fall times are increased (slowed down). The rise/fall times are expressed as a ratio of the clock period. For the ratio of 0.05, the signal is very close to a square wave. For the ratio of 0.45, the rise/fall times are very close to near-triangular waveform. These results, for example, show that the 11th clock harmonic can be reduced by 35 dB if the rise/fall edge is increased from 5% of the period to 45% of the period.

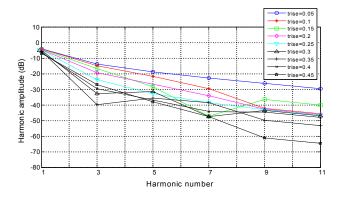


Figure 13. Harmonic EMI reduction as a Function of Slower Rise/Fall Time

### Jitter Reduction with Faster Rise/Fall Time

Power supply noise can be a source of jitter for the downstream chipset. One way to reduce this jitter is to increase rise/fall time (edge rate) of the input clock. Some chipsets would require faster rise/fall time in order to reduce their sensitivity to this type of jitter. The SiT8008 provides up to 3 additional high drive strength settings for very fast rise/fall time. Refer to the Rise/Fall Time Tables to determine the proper drive strength.

### **High Output Load Capability**

The rise/fall time of the input clock varies as a function of the actual capacitive load the clock drives. At any given drive strength, the rise/fall time becomes slower as the output load increases. As an example, for a 3.3V SiT8008 device with default drive strength setting, the typical rise/fall time is 1ns for 15 pF output load. The typical rise/fall time slows down to 2.6ns when the output load increases to 45 pF. One can

choose to speed up the rise/fall time to 1.68ns by then increasing the drive strength setting on the SiT8008.

The SiT8008 can support up to 60 pF or higher in maximum capacitive loads with up to 3 additional drive strength settings. Refer to the Rise/Tall Time Tables to determine the proper drive strength for the desired combination of output load vs. rise/fall time

### SiT8008 Drive Strength Selection

Tables 1 through 5 define the rise/fall time for a given capacitive load and supply voltage.

- 1. Select the table that matches the SiT8008 nominal supply voltage (1.8V, 2.5V, 2.8V, 3.0V, 3.3V).
- 2. Select the capacitive load column that matches the application requirement (5 pF to 60 pF)
- 3. Under the capacitive load column, select the desired rise/fall times.
- 4. The left-most column represents the part number code for the corresponding drive strength.
- 5. Add the drive strength code to the part number for ordering purposes.

### **Calculating Maximum Frequency**

Based on the rise and fall time data given in Tables 1 through 4, the maximum frequency the oscillator can operate with guaranteed full swing of the output voltage over temperature as follows:

Max Frequency = 
$$\frac{1}{6 \times (\text{Trise})}$$

### Example 1

Calculate f<sub>MAX</sub> for the following condition:

- Vdd = 1.8V (Table 1)
- · Capacitive Load: 30 pF
- Desired Tr/f time = 3 ns (rise/fall time part number code = E)

Part number for the above example:

SiT8008AIE12-18E-25.000000T



Drive strength code is inserted here. Default setting is "-"



# Rise/Fall Time (20% to 80%) vs $C_{\text{LOAD}}$ Tables

Rise/Fall Time Typ (ns)								
Drive Strength \ C <sub>LOAD</sub>	5 pF	15 pF	30 pF	45 pF	60 pF			
L	6.16	11.61	22.00	31.27	39.91			
Α	3.19	6.35	11.00	16.01	21.52			
R	2.11	4.31	7.65	10.77	14.47			
В	1.65	3.23	5.79	8.18	11.08			
T	0.93	1.91	3.32	4.66	6.48			
E	0.78	1.66	2.94	4.09	5.74			
U	0.70	1.48	2.64	3.68	5.09			
F or "-": default	0.65	1.30	2.40	3.35	4.56			

Rise/Fall Time Typ (ns)								
Drive Strength \ C <sub>LOAD</sub>	5 pF	15 pF	30 pF	45 pF	60 pF			
L	4.13	8.25	12.82	21.45	27.79			
Α	2.11	4.27	7.64	11.20	14.49			
R	1.45	2.81	5.16	7.65	9.88			
В	1.09	2.20	3.88	5.86	7.57			
T	0.62	1.28	2.27	3.51	4.45			
E or "-": default	0.54	1.00	2.01	3.10	4.01			
U	0.43	0.96	1.81	2.79	3.65			
F	0.34	0.88	1.64	2.54	3.32			

Table 1. Vdd = 1.8V Rise/Fall Times for Specific  $C_{LOAD}$ 

Table 2. Vdd = 2.5V Rise/Fall Times for Specific  $C_{LOAD}$ 

Rise/Fall Time Typ (ns)								
Drive Strength $\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	5 pF	15 pF	30 pF	45 pF	60 pF			
L	3.77	7.54	12.28	19.57	25.27			
Α	1.94	3.90	7.03	10.24	13.34			
R	1.29	2.57	4.72	7.01	9.06			
В	0.97	2.00	3.54	5.43	6.93			
T	0.55	1.12	2.08	3.22	4.08			
E or "-": default	0.44	1.00	1.83	2.82	3.67			
U	0.34	0.88	1.64	2.52	3.30			
F	0.29	0.81	1.48	2.29	2.99			

Rise/Fall Time Typ (ns)								
Drive Strength $\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	5 pF	15 pF	30 pF	45 pF	60 pF			
L	3.60	7.21	11.97	18.74	24.30			
Α	1.84	3.71	6.72	9.86	12.68			
R	1.22	2.46	4.54	6.76	8.62			
В	0.89	1.92	3.39	5.20	6.64			
T or "-": default	0.51	1.00	1.97	3.07	3.90			
E	0.38	0.92	1.72	2.71	3.51			
U	0.30	0.83	1.55	2.40	3.13			
F	0.27	0.76	1.39	2.16	2.85			

Table 3. Vdd = 2.8V Rise/Fall Times for Specific  $C_{LOAD}$ 

Table 4. Vdd = 3.0V Rise/Fall Times for Specific  $C_{LOAD}$ 

Rise/Fall Time Typ (ns)								
Drive Strength $\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	Drive Strength \ C <sub>LOAD</sub> 5 pF 15 pF 30 pF 45 pF 60 pF							
L	3.39	6.88	11.63	17.56	23.59			
Α	1.74	3.50	6.38	8.98	12.19			
R	1.16	2.33	4.29	6.04	8.34			
В	0.81	1.82	3.22	4.52	6.33			
T or "-": default	0.46	1.00	1.86	2.60	3.84			
E	0.33	0.87	1.64	2.30	3.35			
U	0.28	0.79	1.46	2.05	2.93			
F	0.25	0.72	1.31	1.83	2.61			

Table 5. Vdd = 3.3V Rise/Fall Times for Specific  $C_{LOAD}$ 

# **Low Power Programmable Oscillator**



# Instant Samples with Time Machine and Field Programmable Oscillators

SiTime supports a field programmable version of the SiT8008 low power oscillator for fast prototyping and real time customization of features. The <u>field programmable devices</u> (FP devices) are available for all five standard SiT8008 package sizes and can be configured to one's exact specification using the <u>Time Machine II</u>, an USB powered MEMS oscillator programmer.

### Customizable Features of the SiT8008 FP Devices Include

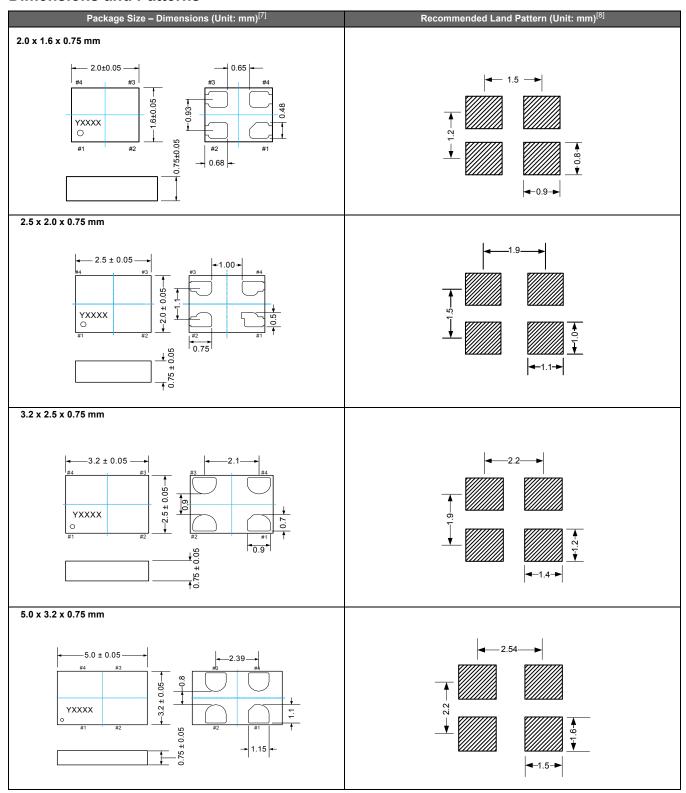
- Any frequency between 1 110 MHz
- Three frequency stability options, ±20 PPM, ±25 PPM, ±50 PPM
- Two operating temperatures, -20 to 70°C or -40 to 85°C
- Five supply voltage options, 1.8V, 2.5V, 2.8V, 3.0V, 3.3V and 2.25 to 3.65V continuous
- · Output drive strength

For more information regarding SiTime's field programmable solutions, visit <a href="http://www.sitime.com/time-machine">http://www.sitime.com/time-machine</a> and <a href="http://www.sitime.com/fp-devices">http://www.sitime.com/fp-devices</a>.

SiT8008 is typically factory-programmed per customer ordering codes for volume delivery.



### **Dimensions and Patterns**

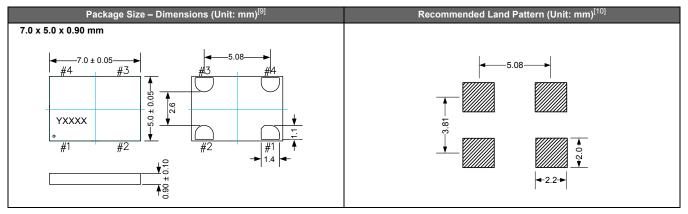


- 7. Top marking: Y denotes manufacturing origin and XXXX denotes manufacturing lot number. The value of "Y" will depend on the assembly location of the device. 8. A capacitor value of 0.1 µF between Vdd and GND is recommended.

# **Low Power Programmable Oscillator**



### **Dimensions and Patterns**

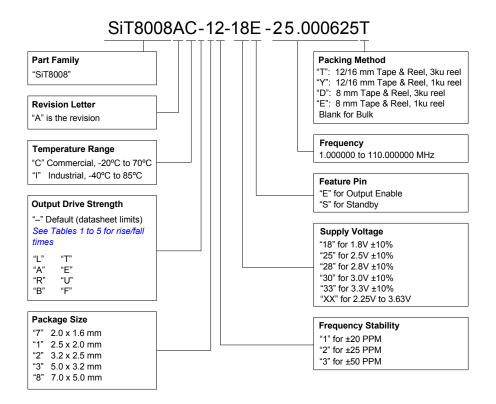


### Notes:

9.Top marking: Y denotes manufacturing origin and XXXX denotes manufacturing lot number. The value of "Y" will depend on the assembly location of the device. 10.A capacitor value of 0.1 µF between Vdd and GND is recommended.



## **Ordering Information**



# Ordering Codes for Supported Tape & Reel Packing Method<sup>[11]</sup>

Device Size	8 mm T&R (3ku)	8 mm T&R (1ku)	12 mm T&R (3ku)	12 mm T&R (1ku)	16 mm T&R (3ku)	16 mm T&R (1ku)
2.0 x 1.6 mm	D	E	-	-	-	-
2.5 x 2.0 mm	D	E	-	-	-	-
3.2 x 2.5 mm	D	E	-	-	-	-
5.0 x 3.2 mm	-	-	Т	Y	-	-
7.0 x 5.0 mm	-	-	-	-	Т	Y

#### Note

11. For "-", contact SiTime for availability.

## Low Power Programmable Oscillator



### **Additional Information**

Document	Description	Download Link		
Time Machine II	MEMS oscillator programmer	http://www.sitime.com/support/time-machine-oscillator-programmer		
Field Programmable Oscillators	Devices that can be programmable in the field by Time Machine II	http://www.sitime.com/products/field-programmable-oscillators		
Manufacturing Notes	Tape & Reel dimension, reflow profile and other manufacturing related info	http://www.sitime.com/component/docman/doc_download/85-manu facturing-notes-for-sitime-oscillators		
Qualification Reports	RoHS report, reliability reports, composition reports	http://www.sitime.com/support/quality-and-reliability		
Performance Reports	Additional performance data such as phase noise, current consumption and jitter for selected frequencies	http://www.sitime.com/support/performance-measurement-report		
Termination Techniques	Termination design recommendations	http://www.sitime.com/support/application-notes		
Layout Techniques	Layout recommendations	http://www.sitime.com/support/application-notes		

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# **Supplemental Information**

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# Silicon MEMS Outperforms Quartz

# Silicon MEMS Outperforms Quartz



### **Best Reliability**

Silicon is inherently more reliable than quartz. Unlike quartz suppliers, SiTime has in-house MEMS and analog CMOS expertise, which allows SiTime to develop the most reliable products. Figure 1 shows a comparison with quartz technology.

### Why is SiTime Best in Class:

- SiTime's MEMS resonators are vacuum sealed using an advanced Epi-Seal™ process, which eliminates foreign particles and improves long term aging and reliability
- · World-class MEMS and CMOS design expertise

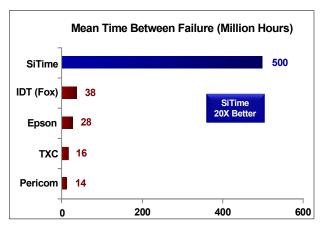


Figure 1. Reliability Comparison<sup>[1]</sup>

### **Best Aging**

Unlike quartz, MEMS oscillators have excellent long term aging performance which is why every new SiTime product specifies 10-year aging. A comparison is shown in Figure 2.

### Why is SiTime Best in Class:

- SiTime's MEMS resonators are vacuum sealed using an advanced Epi-Seal™ process, which eliminates foreign particles and improves long term aging and reliability
- Inherently better immunity of electrostatically driven MEMS resonator

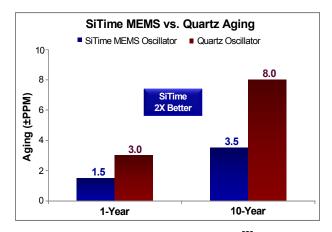


Figure 2. Aging Comparison<sup>[2]</sup>

### Best Electro Magnetic Susceptibility (EMS)

SiTime's oscillators in plastic packages are up to 54 times more immune to external electromagnetic fields than quartz oscillators as shown in Figure 3.

### Why is SiTime Best in Class:

- Internal differential architecture for best common mode noise rejection
- Electrostatically driven MEMS resonator is more immune to EMS

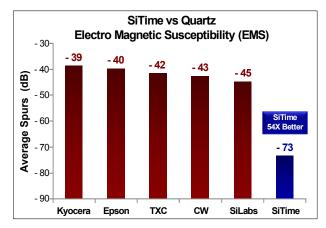


Figure 3. Electro Magnetic Susceptibility (EMS)[3]

### **Best Power Supply Noise Rejection**

SiTime's MEMS oscillators are more resilient against noise on the power supply. A comparison is shown in Figure 4.

### Why is SiTime Best in Class:

- On-chip regulators and internal differential architecture for common mode noise rejection
- · Best analog CMOS design expertise

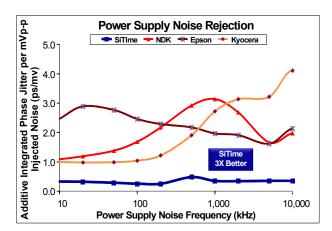


Figure 4. Power Supply Noise Rejection<sup>[4]</sup>

# Silicon MEMS Outperforms Quartz



### **Best Vibration Robustness**

High-vibration environments are all around us. All electronics, from handheld devices to enterprise servers and storage systems are subject to vibration. Figure 5 shows a comparison of vibration robustness.

### Why is SiTime Best in Class:

- The moving mass of SiTime's MEMS resonators is up to 3000 times smaller than guartz
- Center-anchored MEMS resonator is the most robust design

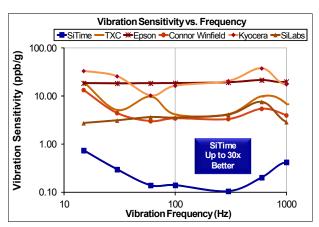


Figure 5. Vibration Robustness<sup>[5]</sup>

#### Notes:

- 1. Data Source: Reliability documents of named companies.
- 2. Data source: SiTime and quartz oscillator devices datasheets.
- 3. Test conditions for Electro Magnetic Susceptibility (EMS):
  - According to IEC EN61000-4.3 (Electromagnetic compatibility standard)
  - Field strength: 3V/m
  - Radiated signal modulation: AM 1 kHz at 80% depth
  - Carrier frequency scan: 80 MHz 1 GHz in 1% steps
  - · Antenna polarization: Vertical
  - DUT position: Center aligned to antenna

### Devices used in this test:

SiTime, SiT9120AC-1D2-33E156.250000 - MEMS based - 156.25 MHz

Epson, EG-2102CA 156.2500M-PHPAL3 - SAW based - 156.25 MHz

TXC, BB-156.250MBE-T - 3rd Overtone quartz based - 156.25 MHz

Kyocera, KC7050T156.250P30E00 - SAW based - 156.25 MHz

Connor Winfield (CW), P123-156.25M - 3rd overtone quartz based - 156.25 MHz

SiLabs, Si590AB-BDG - 3rd overtone quartz based - 156.25 MHz

4. 50 mV pk-pk Sinusoidal voltage.

#### Devices used in this test:

SiTime, SiT8208AI-33-33E-25.000000, MEMS based - 25 MHz

NDK, NZ2523SB-25.6M - quartz based - 25.6 MHz

Kyocera, KC2016B25M0C1GE00 - quartz based - 25 MHz

Epson, SG-310SCF-25M0-MB3 - quartz based - 25 MHz

- 5. **Devices used in this test:** same as EMS test stated in Note 3.
- 6. Test conditions for shock test:
  - MIL-STD-883F Method 2002
  - Condition A: half sine wave shock pulse, 500-g, 1ms
  - $\bullet$  Continuous frequency measurement in 100  $\mu s$  gate time for 10 seconds

Devices used in this test: same as EMS test stated in Note 3

7. Additional data, including setup and detailed results, is available upon request to qualified customers. Please contact productsupport@sitime.com.

### **Best Shock Robustness**

SiTime's oscillators can withstand at least  $50,000\ g$  shock. They all maintain their electrical performance in operation during shock events. A comparison with quartz devices is shown in Figure 6.

### Why is SiTime Best in Class:

- The moving mass of SiTime's MEMS resonators is up to 3000 times smaller than guartz
- Center-anchored MEMS resonator is the most robust design

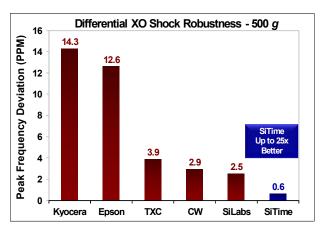


Figure 6. Shock Robustness<sup>[6]</sup>

# **Document Feedback Form**



SiTime values your input in improving our documentation. Click  $\underline{\text{here}}$  for our online feedback form or fill out and email the form below to  $\underline{\text{productsupport@sitime.com}}$ 

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